

## Silicon P-Channel Power MOSFET

### Description

The MDT30P10D uses advanced technology and design to provide excellent  $R_{DS(ON)}$ . It can be used in a wide variety of applications.

### General Features

- $V_{DS}=-110V$ ,  $I_D=-30A$
- Low ON Resistance
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Application

- Power switching application
- Adapter and charger



### Electrical Characteristics @ $T_a=25^\circ C$ (unless otherwise specified)

#### a) Absolute Maximum Ratings:

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-to-Source Breakdown Voltage	-110	V
$I_D$	Drain Current (continuous) at $T_c=25^\circ C$	-30	A
$I_{DM}$	Drain Current (pulsed)	-120	A
$V_{GS}$	Gate to Source Voltage	+/-20	V
$P_{tot}$	Total Dissipation at $T_c=25^\circ C$	180	W
$T_j$	Max. Operating Junction Temperature	175	°C
$E_{AS}$	Single Pulse Avalanche Energy	700	mJ

**b) Electrical Parameters:**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V <sub>DS</sub>	Drain-source Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-100			V
R <sub>DS(on)</sub>	Static Drain-to-Source on-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A		26	32	mΩ
V <sub>GS(th)</sub>	Gated Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-2.0	-3.0	V
I <sub>DSS</sub>	Drain to Source leakage Current	V <sub>DS</sub> =-110V, V <sub>GS</sub> = 0V			-1.0	μA
I <sub>GSS(F)</sub>	Gated Body Foward Leakage	V <sub>GS</sub> = +20V			100	nA
I <sub>GSS(R)</sub>	Gated Body Reverse Leakage	V <sub>GS</sub> = -20V			-100	nA
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHZ		2315		pF
C <sub>oss</sub>	Output Capacitance			190		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			11		pF

**c) Switching Characteristics**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-20V,I <sub>D</sub> =-16A, R <sub>G</sub> =10 Ω		28		nS
t <sub>r</sub>	Turn-on Rise Time			21		nS
t <sub>d(off)</sub>	Turn-off Delay Time			62		nS
t <sub>f</sub>	Turn-off Fall Time			32		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-20V I <sub>D</sub> =-16A V <sub>GS</sub> =-10V		40		nC
Q <sub>gs</sub>	Gate-Source Charge			9.2		nC
Q <sub>gd</sub>	Gate-Drain Charge			14		nC

**d) Source-Drain Diode Characteristics**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I <sub>SD</sub>	S-D Current(Body Diode)				-35	A
I <sub>SDM</sub>	Pulsed S-D Current(Body Diode)				-140	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-35A			-1.5	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25 °C,I <sub>F</sub> =-35A di/dt=100A/us			555	nS
Q <sub>rr</sub>	Reverse Recovery Charge				4550	μC
	*Pulse Test: Pulse Width <= 300μs, Duty Cycle< =2%					

Symbol	Parameter	Typ	Units
R <sub>θJC</sub>	Junction-to-Case	2.5	°C/W